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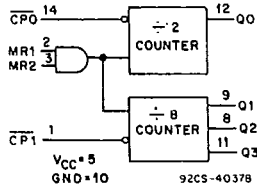
**CD54/74HC93  
CD54/74HCT93**

HARRIS SEMICONDUCTOR 27E D ■ 4302271 0017536 T ■ HAS

**High-Speed CMOS Logic**

T-45-23-13

**4-Bit Binary Ripple Counter**



FUNCTIONAL DIAGRAM

**Type Features:**

- Can be configured to divide by 2, 8, and 16
- Asynchronous Master Reset

The RCA-CD54/74HC93 and the CD54/74HCT93 are high-speed silicon-gate CMOS devices and are pin-compatible with low power Schottky TTL (LSTTL). These 4-bit binary ripple counters consist of four master-slave flip-flops internally connected to provide a divide-by-two section and a divide-by-eight section. Each section has a separate clock input (CP0 and CP1) to initiate state changes of the counter on the HIGH-to-LOW clock transition. State changes of the Qn outputs do not occur simultaneously because of internal ripple delays. Therefore, decoded output signals are subject to decoding spikes and should not be used for clocks or strobes.

A gated AND asynchronous master reset (MR1 and MR2) is provided which overrides both clocks and resets (clears) all flip-flops.

Because the output from the divide-by-two section is not internally connected to the succeeding stages, the device may be operated in various counting modes.

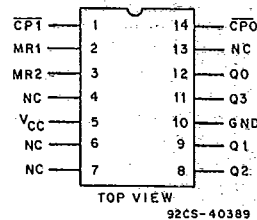
In a 4-bit ripple counter the output Q0 must be connected externally to input CP1. The input count pulses are applied to clock input CP0. Simultaneous frequency divisions of 2, 4, 8, and 16 are performed at the Q0, Q1, Q2, and Q3 outputs as shown in the function table. As a 3-bit ripple counter the input count pulses are applied to input CP1.

Simultaneous frequency divisions of 2, 4, and 8 are available at the Q1, Q2, and Q3 outputs. Independent use of the first flip-flop is available if the reset function coincides with the reset of the 3-bit ripple-through counter.

The CD54HC93 and CD54HCT93 are supplied in 14-lead hermetic dual-in-line frit-seal ceramic packages (F suffix). The CD74HC93 and CD74HCT93 are supplied in 14-lead dual-in-line plastic packages (E suffix) and in 14-lead dual-in-line surface-mount plastic packages (M suffix). Both types are also available in chip form (H suffix).

**Family Features:**

- Fanout (over temperature range):  
Standard outputs - 10 LSTTL loads.  
Bus driver outputs - 15 LSTTL loads
- Wide operating temperature range:  
CD74HC/HCT: -40 to +85°C
- Balanced propagation delay and transition times
- Significant power reduction compared to LSTTL logic ICs
- Alternate source is Philips/Sigmetics
- CD54HC/CD74HC types:  
2 to 6 V operation  
High noise immunity:  
 $N_{IL}=30\%$ ,  $N_{IH}=30\%$  of  $V_{CC}$ ; @  $V_{CC}=5$  V
- CD54HCT/CD74HCT types:  
4.5 to 5.5 V operation  
Direct LSTTL input logic compatibility  
 $V_{IL}=0.8$  V max.,  $V_{IH}=2$  V min.  
CMOS input compatibility  
 $I_L \leq 1 \mu A$  @  $V_{OL}$ ,  $V_{OH}$



TERMINAL ASSIGNMENT

# CD54/74HC93 CD54/74HCT93

**MAXIMUM RATINGS, Absolute-Maximum Values:**

DC SUPPLY-VOLTAGE, ( $V_{CC}$ ):  
(Voltages referenced to ground) ..... -0.5 to +7 V

DC INPUT DIODE CURRENT,  $I_{IK}$  (FOR  $V_I < -0.5$  V OR  $V_I > V_{CC} + 0.5$  V) .....  $\pm 20$  mA

DC OUTPUT DIODE CURRENT,  $I_{OK}$  (FOR  $V_O < -0.5$  V OR  $V_O > V_{CC} + 0.5$  V) .....  $\pm 20$  mA

DC DRAIN CURRENT, PER OUTPUT ( $I_O$ ) (FOR  $-0.5$  V  $< V_O < V_{CC} + 0.5$  V) .....  $\pm 25$  mA

DC  $V_{CC}$  OR GROUND CURRENT ( $I_{CC}$ ) .....  $\pm 50$  mA

POWER DISSIPATION PER PACKAGE ( $P_D$ ):

For  $T_A = -40$  to  $+60^\circ$  C (PACKAGE TYPE E) ..... 500 mW

For  $T_A = +60$  to  $+85^\circ$  C (PACKAGE TYPE E) ..... Derate Linearly at 8 mW/ $^\circ$ C to 300 mW

For  $T_A = -55$  to  $+100^\circ$  C (PACKAGE TYPE F,H) ..... 500 mW

For  $T_A = +100$  to  $+125^\circ$  C (PACKAGE TYPE F,H) ..... Derate Linearly at 8 mW/ $^\circ$ C to 300 mW

For  $T_A = -40$  to  $+70^\circ$  C (PACKAGE TYPE M) ..... 400 mW

For  $T_A = +70$  to  $+125^\circ$  C (PACKAGE TYPE M) ..... Derate Linearly at 6 mW/ $^\circ$ C to 70 mW

OPERATING-TEMPERATURE RANGE ( $T_A$ ):

PACKAGE TYPE F,H .....  $-55$  to  $+125^\circ$  C

PACKAGE TYPE E,M .....  $-40$  to  $+85^\circ$  C

STORAGE TEMPERATURE ( $T_{STG}$ ) .....  $-85$  to  $+150^\circ$  C

LEAD TEMPERATURE (DURING SOLDERING):

At distance  $1/16 \pm 1/32$  in. ( $1.59 \pm 0.79$  mm) from case for 10 s max. ....  $+265^\circ$  C

Unit inserted into a PC Board (min. thickness  $1/16$  in., 1.59 mm) with solder contacting lead tips only .....  $+300^\circ$  C

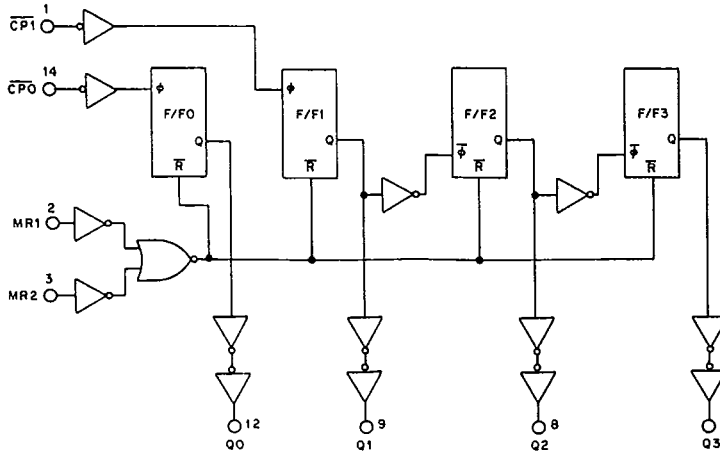


Fig. 1 - HC/HCT93 logic diagram.

**FUNCTION TABLE  
(Q0 connected to CP1)**

COUNT	OUTPUTS			
	Q0	Q1	Q2	Q3
0	L	L	L	L
1	H	L	L	L
2	L	L	H	L
3	H	H	L	L
4	L	L	L	H
5	H	L	H	L
6	L	H	H	L
7	H	H	H	L
8	L	L	L	H
9	H	L	L	H
10	L	H	L	H
11	H	H	L	H
12	L	L	H	H
13	H	L	L	H
14	L	H	H	H
15	H	H	H	H

**MODE SELECTION**

RESET INPUTS		OUTPUTS			
MR1	MR2	Q0	Q1	Q2	Q3
H	H	L	L	L	L
L	H	count			
H	L	count			
L	L	count			

H = HIGH voltage level  
L = LOW voltage level

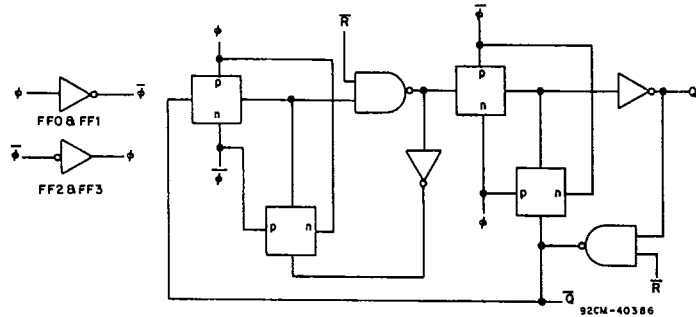


Fig. 2 - Flip-flop (0-3) logic detail.

**CD54/74HC93**  
**CD54/74HCT93**

STATIC ELECTRICAL CHARACTERISTICS

HARRIS SEMICOND SECTOR 27E D 4302271 0017538 3 HAS

CHARACTERISTIC	CD74HC93/CD54HC93										CD74HCT93/CD54HCT93								UNITS			
	TEST CONDITIONS			74HC/54HC TYPES			74HC TYPES		54HC TYPES			TEST CONDITIONS		74HCT/54HCT TYPES			74HCT TYPES			54HCT TYPES		
	V <sub>I</sub> V	I <sub>O</sub> mA	V <sub>CC</sub> V	+25°C			-40/ +85°C		-55/ +125°C			V <sub>I</sub> V	V <sub>CC</sub> V	+25°C			-40/ +85°C			-55/ +125°C		
				Min	Typ	Max	Min	Max	Min	Max	Min			Max	Min	Max	Min	Max		Min	Max	
High-Level Input Voltage	V <sub>IH</sub>			2	1.5	—	—	1.5	—	1.5	—	—	4.5	to	2	—	—	2	—	2	—	V
				4.5	3.15	—	—	3.15	—	3.15	—	—	5.5									
				6	4.2	—	—	4.2	—	4.2	—											
Low-Level Input Voltage	V <sub>IL</sub>			2	—	—	0.5	—	0.5	—	0.5	—	4.5	to	—	—	0.8	—	0.8	—	0.8	V
				4.5	—	—	1.35	—	1.35	—	1.35	—	5.5									
				6	—	—	1.8	—	1.8	—	1.8	—										
High-Level Output Voltage	V <sub>OH</sub>	V <sub>IL</sub> or -0.02		2	1.9	—	—	1.9	—	1.9	—	V <sub>IL</sub> or 4.5	4.4	—	—	4.4	—	4.4	—	4.4	—	V
CMOS Loads	V <sub>IH</sub>			6	5.9	—	—	5.9	—	5.9	—	V <sub>IH</sub>										
TTL Loads	V <sub>IL</sub> or V <sub>DH</sub>			-4	4.5	3.98	—	—	3.84	—	3.7	—	4.5	3.98	—	—	3.84	—	3.7	—	V	
Low-Level Output Voltage	V <sub>OL</sub>	V <sub>IL</sub> or 0.02		2	—	—	0.1	—	0.1	—	0.1	V <sub>IL</sub> or 4.5	—	—	0.1	—	0.1	—	0.1	—	V	
CMOS Loads	V <sub>IH</sub>			6	—	—	0.1	—	0.1	—	0.1	V <sub>IH</sub>										
TTL Loads	V <sub>IL</sub> or V <sub>IH</sub>			4	4.5	—	—	0.26	—	0.33	—	4.5	—	—	0.26	—	0.33	—	0.4	—	V	
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> or Gnd		6	—	—	±0.1	—	±1	—	±1	Any Voltage Between V <sub>CC</sub> & Gnd	5.5	—	—	±0.1	—	±1	—	±1	μA	
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or Gnd	0	6	—	—	8	—	80	—	160	V <sub>CC</sub> or Gnd	5.5	—	—	8	—	80	—	160	μA	
Additional Quiescent Device Current per input pin: 1 unit load ΔI <sub>CC</sub> *												V <sub>CC</sub> -2.1	4.5 to 5.5	—	100	360	—	450	—	490	μA	

\*For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4 V, V<sub>CC</sub> = 5.5 V) specification is 1.8 mA.

HCT INPUT LOADING TABLE

INPUT	UNIT LOADS*
CP0, CP1	0.6
MR1, MR2	0.4

\*Unit Load is ΔI<sub>CC</sub> limit specified in Static Characteristics Chart, e.g. 360 μA max. @ 25°C.

**CD54/74HC93**  
**CD54/74HCT93**

**RECOMMENDED OPERATING CONDITIONS**

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range (For T <sub>A</sub> =Full Package Temperature Range) V <sub>CC</sub> .*			
CD54/74HC Types	2	6	V
CD54/74HCT Types	4.5	5.5	V
DC Input or Output Voltage, V <sub>I</sub> , V <sub>O</sub>	0	V <sub>CC</sub>	V
Operating Temperature, T <sub>A</sub> :			
CD74 Types	-40	+85	°C
CD54 Types	-55	+125	°C
Input Rise and Fall Times, t <sub>r</sub> , t <sub>f</sub> :			
at 2 V	0	1000	ns
at 4.5 V	0	500	
at 6 V	0	400	

\*Unless otherwise specified, all voltages are referenced to Ground.

**SWITCHING CHARACTERISTICS (V<sub>CC</sub>=5 V, T<sub>A</sub>=25° C, Input t<sub>r</sub>, t<sub>f</sub>=6 ns)**

CHARACTERISTIC	C <sub>L</sub> (pF)	TYPICAL VALUES		UNITS
		HC	HCT	
Propagation Delay:				
CP0 to Q0 Output	15	10	14	ns
CP1 to Q3		21	24	
MRn to Qn Output		13	13	
Power Dissipation Capacitance*	C <sub>PD</sub>	25	25	pF

\*C<sub>PD</sub> is used to determine the dynamic power consumption, per counter.

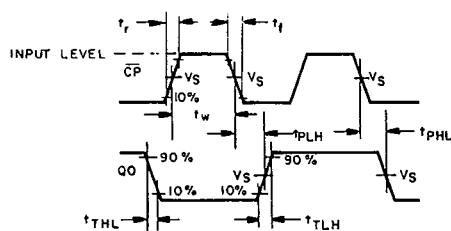
$P_D = C_{PD} V_{CC}^2 f_i + \sum C_L V_{CC}^2 f_o$  where  
 f<sub>i</sub> = input frequency  
 f<sub>o</sub> = output frequency  
 C<sub>L</sub> = output load capacitance  
 V<sub>CC</sub> = supply voltage.

**PRE-REQUISITE FOR SWITCHING FUNCTION**

CHARACTERISTIC	TEST CONDITIONS	LIMITS												UNITS				
		25° C				-40° C to +85° C				-55° C to +125° C								
		HC		HCT		74HC		74HCT		54HC		54HCT						
V <sub>CC</sub> (V)	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.						
Maximum Clock Frequency	f <sub>MAX</sub>	2	6	—	—	—	—	5	—	—	—	—	—	4	—	—	—	MHz
		4.5	30	—	30	—	—	24	—	24	—	—	—	20	—	20	—	
		6	35	—	—	—	—	28	—	—	—	—	—	24	—	—	—	
Clock Pulse Width	t <sub>w</sub>	2	80	—	—	—	—	100	—	—	—	—	—	120	—	—	—	ns
	CP0, CP1	4.5	16	—	16	—	—	20	—	20	—	—	—	24	—	24	—	
		6	14	—	—	—	—	17	—	—	—	—	—	20	—	—	—	
Reset Pulse Width	t <sub>w</sub>	2	80	—	—	—	—	100	—	—	—	—	—	120	—	—	—	ns
		4.5	16	—	16	—	—	20	—	20	—	—	—	24	—	24	—	
		6	14	—	—	—	—	17	—	—	—	—	—	20	—	—	—	
Reset Removal Time	t <sub>REM</sub>	2	50	—	—	—	—	65	—	—	—	—	—	75	—	—	—	ns
		4.5	10	—	10	—	—	13	—	13	—	—	—	15	—	15	—	
		6	9	—	—	—	—	11	—	—	—	—	—	13	—	—	—	

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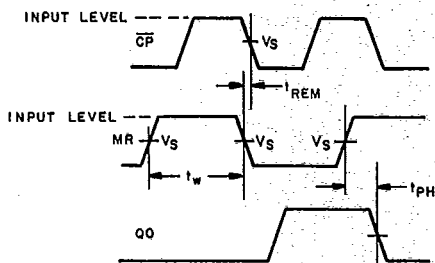
**CD54/74HC93**  
**CD54/74HCT93**



	54/74HC	54/74HCT
INPUT LEVEL	V <sub>CC</sub>	3 V
SWITCHING VOLTAGE, V <sub>S</sub>	50% V <sub>CC</sub>	1.3 V

92CS-38370R2

Fig. 3 - Pre-requisite, propagation-delay, and output-transition times.



	54/74HC	54/74HCT
INPUT LEVEL	V <sub>CC</sub>	3 V
SWITCHING VOLTAGE, V <sub>S</sub>	50%	1.3 V

92CS-38371R2

Fig. 4 - Master-Reset pre-requisite and propagation-delay times.

**SWITCHING CHARACTERISTICS (C<sub>L</sub>=50 pF, Input t<sub>r</sub>,t<sub>f</sub>=6 ns)**

CHARACTERISTIC	V <sub>CC</sub>	LIMITS												UNITS	
		25° C				-40° C to +85° C				-55° C to +125° C					
		HC		HCT		74HC		74HCT		54HC		54HCT			
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.		
Propagation Delay Time:	t <sub>PLH</sub>	2	—	125	—	—	—	155	—	—	—	190	—	—	ns
	t <sub>PHL</sub>	4.5	—	25	—	34	—	31	—	43	—	38	—	51	
	CP0 to Q0	6	—	21	—	—	—	26	—	—	—	32	—	—	
CP1 to Q1	2	—	135	—	—	—	170	—	—	—	205	—	—		
	4.5	—	27	—	34	—	34	—	43	—	41	—	51		
	6	—	23	—	—	—	29	—	—	—	35	—	—		
CP1 to Q2	2	—	185	—	—	—	230	—	—	—	280	—	—		
	4.5	—	37	—	46	—	46	—	58	—	56	—	69		
	6	—	31	—	—	—	39	—	—	—	48	—	—		
CP1 to Q3	2	—	245	—	—	—	305	—	—	—	370	—	—		
	4.5	—	49	—	58	—	61	—	73	—	74	—	87		
	6	—	42	—	—	—	52	—	—	—	63	—	—		
MR1, MR2 to Qn	2	—	155	—	—	—	195	—	—	—	235	—	—		
	4.5	—	31	—	33	—	39	—	41	—	47	—	50		
	6	—	26	—	—	—	33	—	—	—	40	—	—		
Output Transition Time	t <sub>THL</sub>	2	—	75	—	—	—	95	—	—	—	110	—	—	
	t <sub>TLH</sub>	4.5	—	15	—	15	—	19	—	19	—	22	—	22	
	6	—	13	—	—	—	16	—	—	—	19	—	—		
Input Capacitance	C <sub>i</sub>		—	10	—	10	—	10	—	10	—	10	—	pF	

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